

Cookson Group Plaskon® S-7S Epoxy Encapsulant (discontinued **)

Category : Polymer , Thermoset , Epoxy , Epoxy Encapsulant, Unreinforced

Material Notes:

Test specimens were transfer molded and post cured 4 hours at 175°C. A low stress, low viscosity epoxy encapsulant designed for packaging stress-sensitive semiconductor devices. It is specifically formulated to provide a lower viscosity for those low stress applications where wire sweep may be a concern. Excellent low stress properties; Consistent moldability (low viscosity, easy of mold filling, fast cycles and good hot hardness); Outstanding cosmetics and markability; Superior reliability

Order this product through the following link:

http://www.lookpolymers.com/polymer_Cookson-Group-Plaskon-S-7S-Epoxy-Encapsulant-nbspdiscontinued-.php

Physical Properties	Metric	English	Comments
Density	1.82 g/cc	0.0658 lb/in ³	
Viscosity	8500 cP @Temperature 175 °C	8500 cP @Temperature 347 °F	Automatic orifice Viscosity
Linear Mold Shrinkage	0.0037 cm/cm	0.0037 in/in	
Spiral Flow	80.0 - 110 cm	31.5 - 43.3 in	177°C/1000 psi

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	73	73	
Tensile Strength, Ultimate	62.0 MPa	8990 psi	
Flexural Strength	110 MPa	16000 psi	
Flexural Modulus	13.0 GPa	1890 ksi	

Thermal Properties	Metric	English	Comments
CTE, linear	18.5 µm/m-°C @Temperature 20.0 °C	10.3 µin/in-°F @Temperature 68.0 °F	
CTE, linear, Transverse to Flow	70.0 µm/m-°C @Temperature 20.0 °C	38.9 µin/in-°F @Temperature 68.0 °F	
Thermal Conductivity	0.700 W/m-K	4.86 BTU-in/hr-ft ² -°F	
Glass Transition Temp, Tg	165 °C	329 °F	
Flammability, UL94	V-0 @Thickness 3.20 mm	V-0 @Thickness 0.126 in	
	V-0	V-0	

Thermal Properties	Metric	English	Comments
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Electrical Properties	Metric	English	Comments
Dielectric Constant	3.68	3.68	
	@Frequency 1000 Hz	@Frequency 1000 Hz	
Dielectric Strength	16.0 kV/mm	406 kV/in	
Dissipation Factor	0.0020	0.0020	
	@Frequency 1000 Hz	@Frequency 1000 Hz	
Arc Resistance	180 sec	180 sec	

Processing Properties	Metric	English	Comments
Processing Temperature	170 - 185 °C	338 - 365 °F	Molding temperature

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China